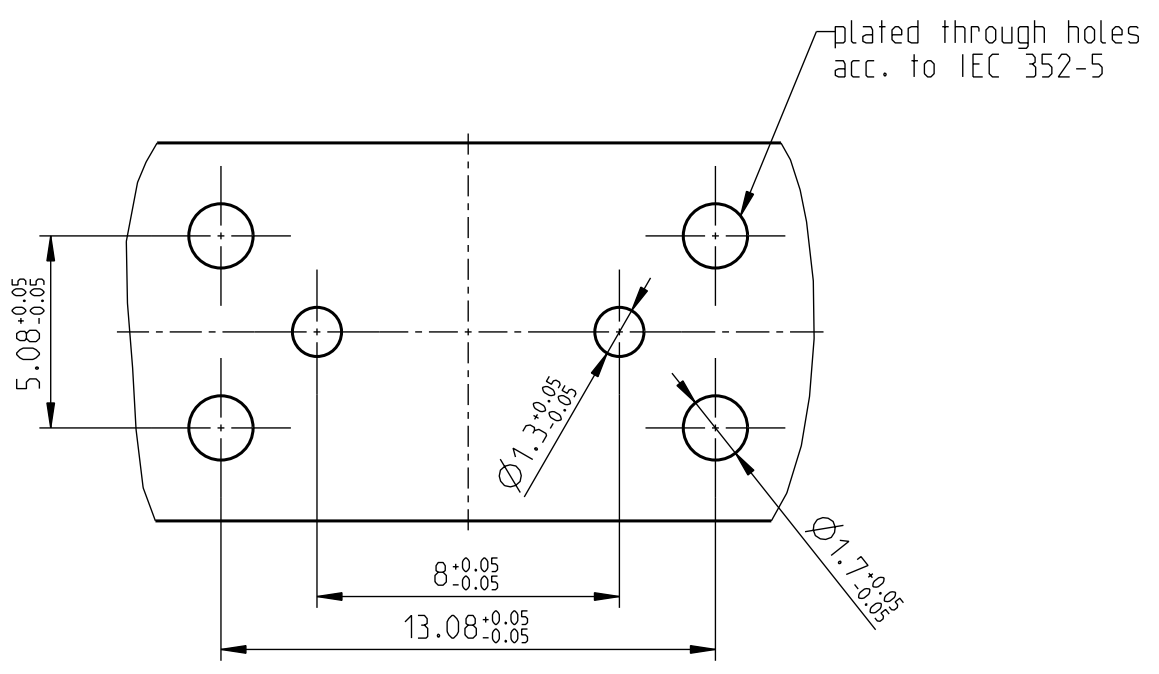


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Leiterplatten-Layout
PCB layout
B 187
fuer Schwallbad-Loeten
for wave soldering



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A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Format: TCC-FB-05-PL-A4 Einzelteil
Date: 15.06.2011 13:58:00
Version: 1.1

Dimensions in mm

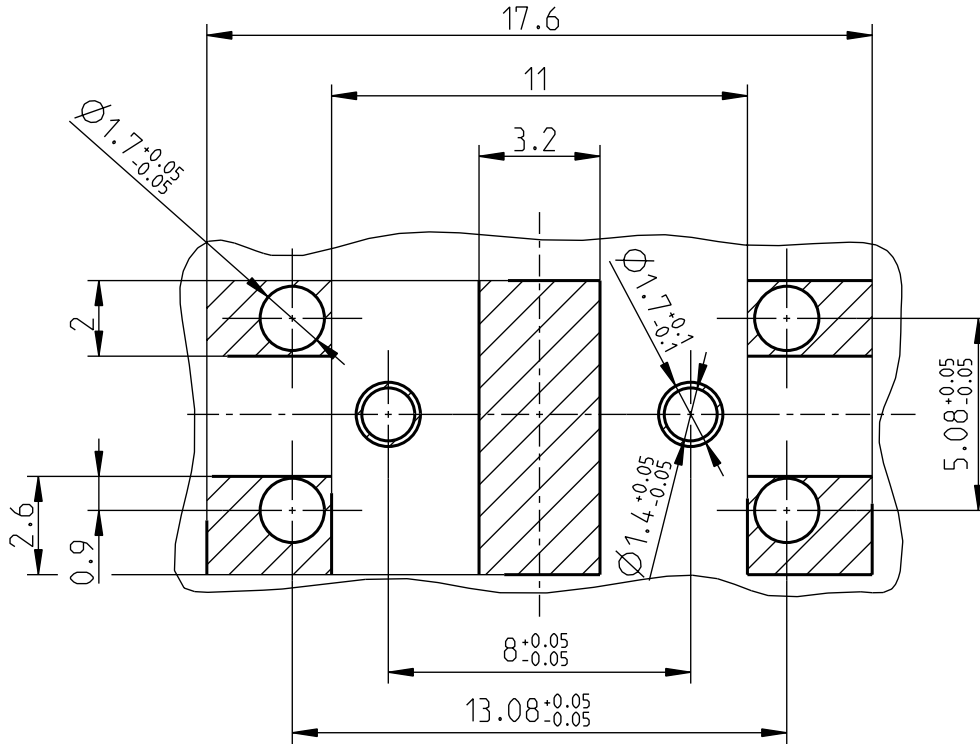


ISO-Projektion Methode E

<h2 style="margin: 0;">Rosenberger</h2> <p style="margin: 0; font-size: small;">Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER</p>		<i>general tolerance</i> ISO 2768 RN 006-01 m-H dimensions <0,5 and symmetry		scale: 5:1 ()	weight(g):3.201 surface(mm²):555.6	
		material: CuZn39Pb3		EN 12164		
		<i>date</i> <i>name</i>		<h1 style="margin: 0;">Leiterplatten-Layout PCB layout</h1>		
		<i>drawn</i>	10.11.2005 T_Oberschelp			
		<i>check</i>	17.04.2012 M_Singhammer			
		<i>appr.</i>	17.04.2012 T_Hoefling			
		dimensioning incl. finish		drawing-no... MB_187		
400	12-0322	A_Kott	17.04.2012			sheet: 1
300	09-0817	M_Singhammer	25.11.2009	of: 2		
200	06-0194	S_Krautenbac	23.06.2006			
100	05-v247	T_Oberschelp	10.11.2005			
rev.	change-no	name	date	distribu- tion to:	remarks: .	
				FE AZ QSM RMT . X 		

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Leiterplatten-Layout
PCB layout
B 187
fuer Reflow-Loeten
for reflow soldering



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A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Format: TCC-FB-05-PE-AA-Entwurf
Date: 17.04.2012 11:00 AM
Version: 1.1

Dimensions
in mm



ISO-Projektion
Methode E

<h2 style="margin: 0;">Rosenberger</h2> <p style="margin: 0; font-size: small;">Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER</p>		<i>general tolerance</i> ISO 2768 RN 006-01 m-H dimensions <0,5 and symmetry		<i>scale:</i> 5:1 ()	<i>weight(g):</i> 3.193 <i>surface(mm²):</i> 556.0
		<i>material:</i> CuZn39Pb3 EN 12164			
		<i>date</i> <i>name</i> <i>drawn</i> 10.11.2005 T_Oberschelp <i>check</i> 17.04.2012 M_Singhammer <i>appr.</i> 17.04.2012 T_Hoefling		<h1 style="margin: 0;">Leiterplatten-Layout PCB layout</h1>	
		<i>title:</i> <h2 style="margin: 0;">Leiterplatten-Layout PCB layout</h2>			
		<i>drawing-no...:</i> MB_187		<i>sheet:</i> 2 <i>of:</i> 2	
		<i>remarks:</i> .			

rev.	change-no	name	date	
400	12-0322	A_Kott	17.04.2012	<i>dimensioning incl. finish</i>
300	09-0817	M_Singhammer	25.11.2009	
200	06-0194	S_Krautenbac	23.06.2006	
100	05-v247	T_Oberschelp	10.11.2005	
				<i>distribu- tion to:</i>
				FE AZ QSM RMT . X